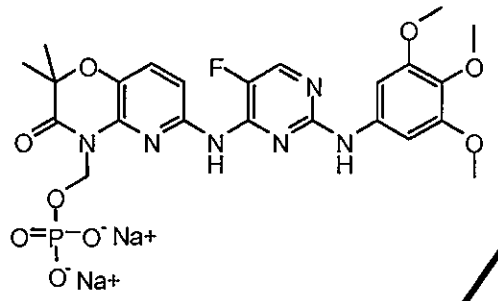
WHAT IS CLAIMED IS:

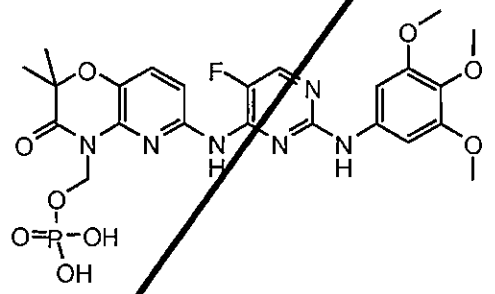
1. A process for preparing a compound of formula I:



I

comprising:

a) contacting an acid solvate of a compound of formula II:



II

with an amide under conditions suitable for forming an amide solvate of the compound of formula II; and

b) contacting the amide solvate with an aqueous base comprising sodium ions under conditions suitable for forming the compound of formula I.

2. The process of Claim 1, wherein the acid component of the acid solvate of the compound of formula II is a carboxylic acid.

3. The process of claim 2, wherein the carboxylic acid is R^1COOH wherein R^1 is -H or a C_1-C_4 alkyl optionally substituted with up to three halo.

4. The process of Claim 1, wherein the amide is a secondary amide or a tertiary amide.

5. The process of claim 4, wherein the amide is $R^{30}CON(R^2)_2$ where each R^2 is independently -H or C_1-C_4 alkyl or both R^2 together with the nitrogen to which they are attached form a 4 to 6 membered aliphatic ring, and R^{30} is -H or C_1-C_4 alkyl; or

R^{30} and one of the R^2 together with the carbon and nitrogen to which they are attached, respectively, combine to form a 4 to 6-membered aliphatic ring and the other R^2 is independently –H or C_1-C_4 alkyl.

6. The process of claim 5, wherein the amide is a N,N-dialkylformamide, N,N-dialkylacetamide, N-alkylpyrrolidinone, or N-alkylpiperidone.

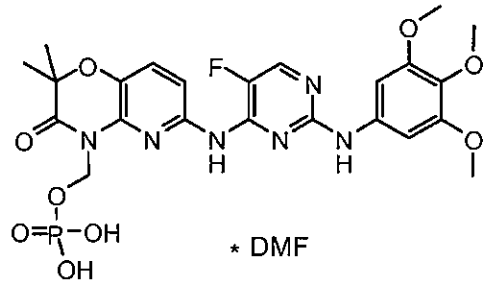
7. The process of Claim 6, wherein the amide is the N,N-dialkylformamide; and the conditions suitable for forming the amide solvate of the compound of formula II comprise a temperature of between about 20 °C and about 70 °C.

8. The process of Claim 7, wherein the amide is N,N-dimethylformamide (DMF); and the conditions suitable for forming the amide solvate comprise re-slurrying of the acid solvate in the DMF at a temperature of about 50 °C.

9. The process of Claim 1, wherein the aqueous base in part b) comprises sodium hydroxide and an alcohol, and the conditions suitable for forming the compound of formula I comprise a temperature of between about 40 °C about 80 °C and a pH of about 8 to about 10.5.

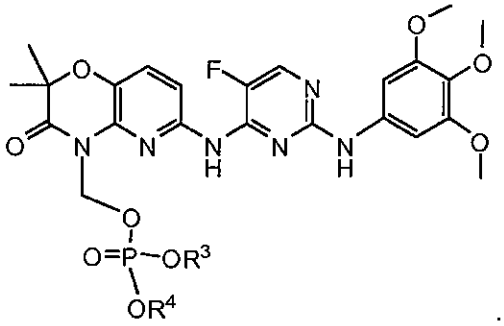
10. The process of Claim 9, wherein the aqueous base in step b) comprises sodium hydroxide (NaOH) and isopropyl alcohol (IPA), and the conditions suitable for forming the compound of formula I comprise a temperature of about 80 °C and a pH of about 9.

11. A compound of formula III:



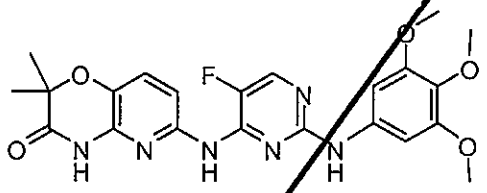
III

12. A process for preparing a compound of formula IV:



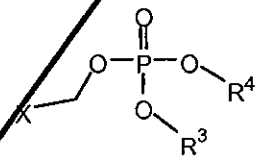
VI

comprising contacting a compound of formula IV:



IV

with a compound of formula V:



V

in the presence of an amide,

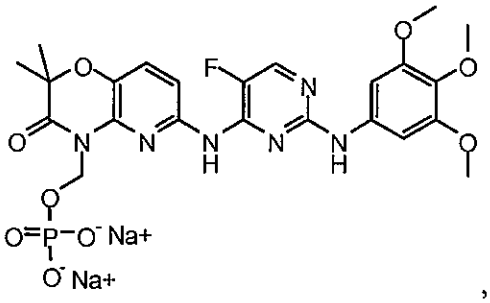
wherein:

R^3 and R^4 are each independently C_1-C_6 alkyl; and

X is halogen;

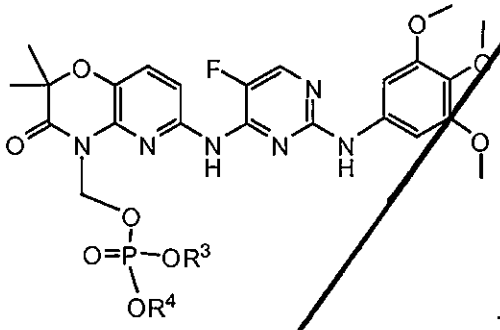
under conditions suitable for forming a compound of formula VI.

13. A method for preparing a compound for formula I,



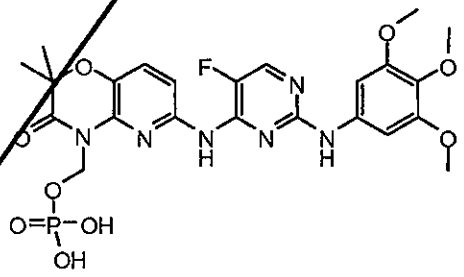
I

comprising contacting a compound of formula VI,



VI

with an acid under conditions suitable for forming an acid solvate of a compound of formula II:

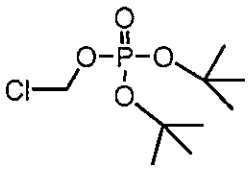


II

contacting the acid solvate of the compound of formula II with an amide under conditions suitable for forming an amide solvate of the compound of formula II; and

contacting the amide solvate of the compound of formula II with an aqueous base comprising sodium ions under conditions suitable for forming the compound of formula I.

14. The process of Claim 12, wherein the compound of formula V is di-*tert*-butyl chloromethyl phosphate:



15. The process of Claim 12, wherein the conditions sufficient to produce the compound of formula VI comprise:

(i) combining the compound of formula IV with the compound of formula V with a base in a polar solvent; and

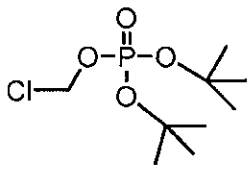
(ii) washing a product obtained from (i) in an aqueous base solution.

16. The process of Claim 15, wherein the base in (i) comprises at least one of cesium carbonate (Cs_2CO_3) and potassium carbonate (K_2CO_3); the polar solvent comprises at least one of DMF and N,N-dimethylacetamide (DMAc); and the aqueous base in (ii) comprises at least one of sodium bicarbonate ($NaHCO_3$) and sodium hydroxide (NaOH).

17. The process of Claim 12, wherein the compound of formula VI is not isolated.

18. The process of Claim 12, wherein the compound of formula V is stabilized with N,N-dimethylacetamide (DMAc) solvent.

19. A composition comprising di-*tert*-butyl chloromethyl phosphate:



and an amide.

20. The composition of claim 19, wherein the amide is also a solvent.

21. The composition of Claim 20, wherein the amide is a tertiary amide.

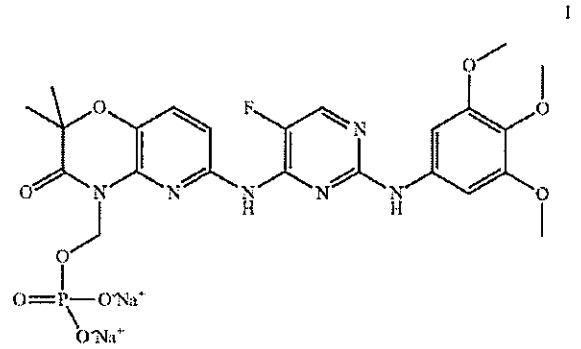
22. The composition of Claim 21wherein the tertiary amide is N,N-dimethylacetamide (DMAc).

23. The process according to claim 1 or 13 wherein the compound of formula I is in the form of a hydrate.

24. The process according to claim 23 wherein the hydrate is a hexahydrate.

WHAT IS CLAIMED IS:

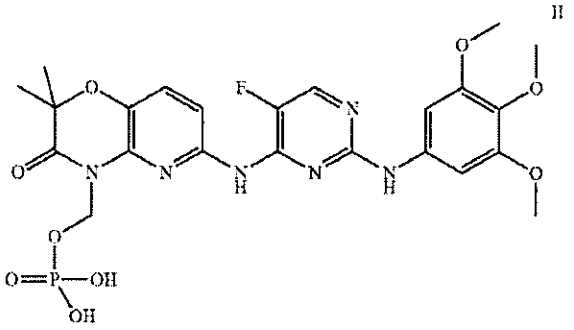
1. A process for preparing a compound of formula I:



I

comprising:

a) contacting an acid solvate of a compound of formula II:



II

with an amide under conditions suitable for forming an amide solvate of the compound of formula II; and

b) contacting the amide solvate with an aqueous base comprising sodium ions under conditions suitable for forming the compound of formula I

wherein the carboxylic acid is R^1COOH wherein R^1 is —H or a C_1-C_4 alkyl optionally substituted with up to three halo; and the amide is $R^{30}CON(R^2)_2$ where each R^2 is independently —H or C_1-C_4 alkyl or both R^2 together with the nitrogen to which they are attached form a 4 to 6 membered aliphatic ring, and R^{30} is —H or C_1-C_4 alkyl; or R^{30} and one of the R^2 together with the carbon and nitrogen to which they are attached, respectively, combine to form a 4 to 6-membered aliphatic ring and the other R^2 is independently —H or C_1-C_4 alkyl.

2. The process of claim 1, wherein the amide is a N,N-dialkylformamide, N,N-dialkylacetamide, N-alkylpyrrolidinone, or N-alkylpiperidone.

3. The process of claim 2, wherein the amide is the N,N-dialkylformamide; and the conditions suitable for forming the amide solvate of the compound of formula II comprise a temperature of between about 20° C. and about 70° C.

4. The process of claim 3, wherein the amide is N,N-dimethylformamide (DMF); and the conditions suitable for forming the amide solvate comprise re-slurrying of the acid solvate in the DMF at a temperature of about 50° C.

5. The process of claim 1, wherein the aqueous base in part b) comprises sodium hydroxide and an alcohol, and the conditions suitable for forming the compound of formula I comprise a temperature of between about 40° C. about 80° C. and a pH of about 8 to about 10.5.

6. The process of claim 5, wherein the aqueous base in step b) comprises sodium hydroxide (NaOH) and isopropyl alcohol (IPA), and the conditions suitable for forming the compound of formula I comprise a temperature of about 80° C. and a pH of about 9.

7. The process according to claim 1 wherein the compound of formula I is in the form of a hydrate.

8. The process according to claim 7 wherein the hydrate is a hexahydrate.